

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Metal silicon junction, majority carrier conduction
- ◆ Low power loss, high efficiency
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:
260°C/10 seconds
- ◆ Compliant to RoHS Directive 2011/65/EU
- ◆ Compliant to Halogen-free



PowerDI-123

Mechanical data

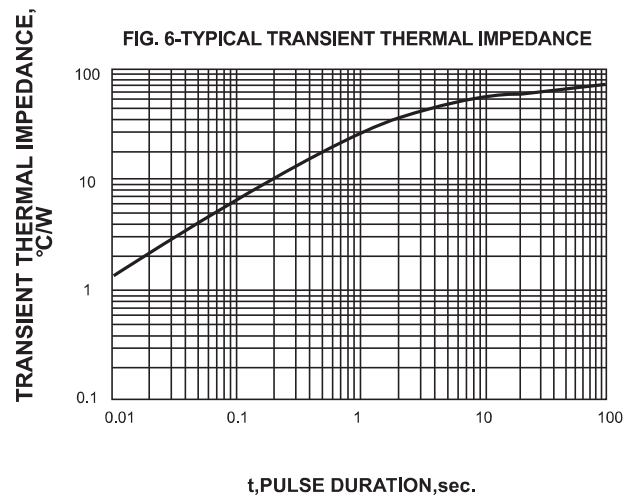
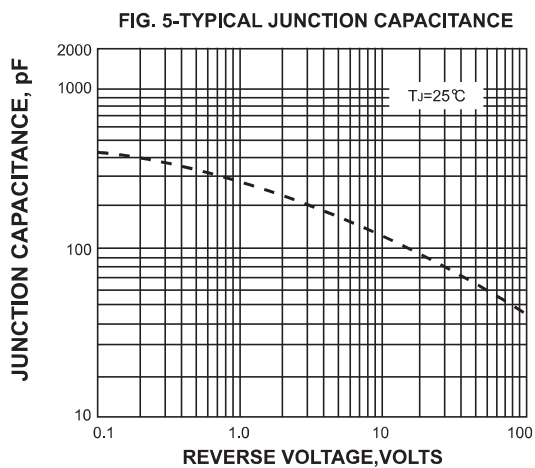
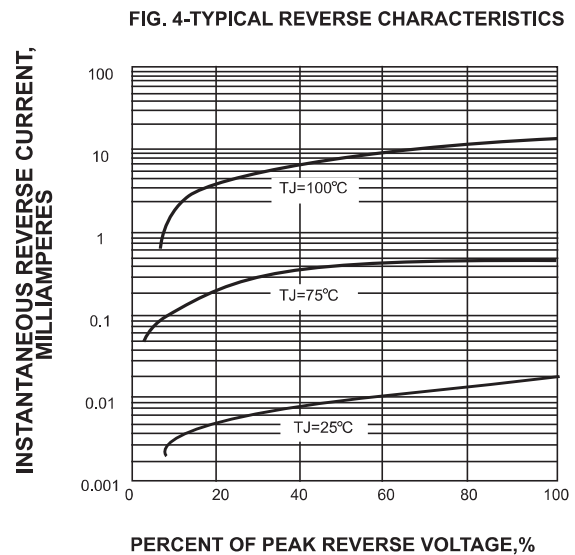
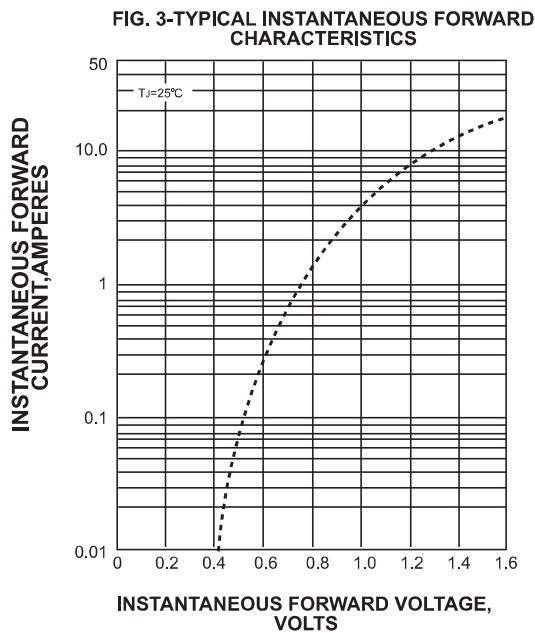
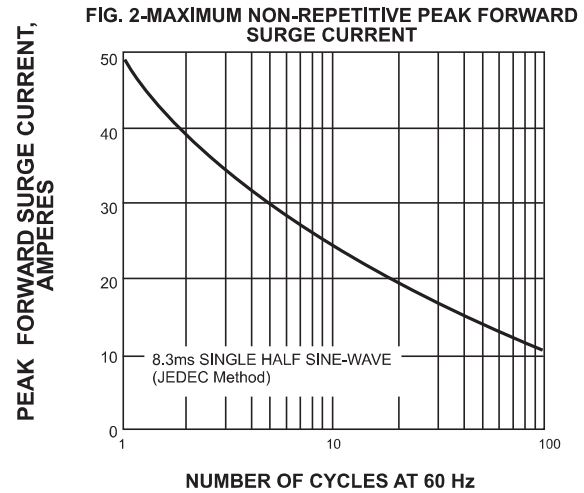
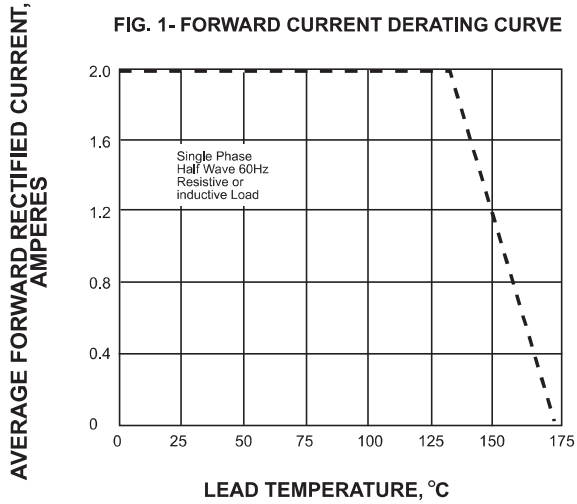
- ◆ **Case**: JEDEC PowerDI-123 molded plastic body
- ◆ **Terminals**: Plated axial leads, solderable per MIL-STD-750, Method 2026
- ◆ **Polarity**: Color band denotes cathode end
- ◆ **Mounting Position**: Any

Maximum ratings and Electrical Characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	DFLS1100	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	100	V
Maximum RMS voltage	V_{RMS}	71	V
Maximum DC blocking voltage	V_{DC}	100	V
Maximum average forward rectified current at T_L (see fig.1)	$I_{(AV)}$	2.0	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	50	A
Maximum instantaneous forward voltage at 1.0A	V_F	0.77	V
Maximum instantaneous forward voltage at 2.0A	V_F	0.85	V
Maximum DC reverse current $T_A=25^{\circ}\text{C}$ at rated DC blocking voltage $T_A=100^{\circ}\text{C}$	I_R	1	uA
		0.35	mA
Typical junction capacitance (NOTE 1)	C_J	220	pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	85	$^{\circ}\text{C/W}$
Operating junction temperature range	T_{JL}	-55 to +175	$^{\circ}\text{C}$
Storage temperature range	T_{STG}	-55 to +175	$^{\circ}\text{C}$

Note:1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2.P.C.B. mounted with 2.0x2.0" (5.0x5.0cm) copper pad areas

Rating and characteristic curves



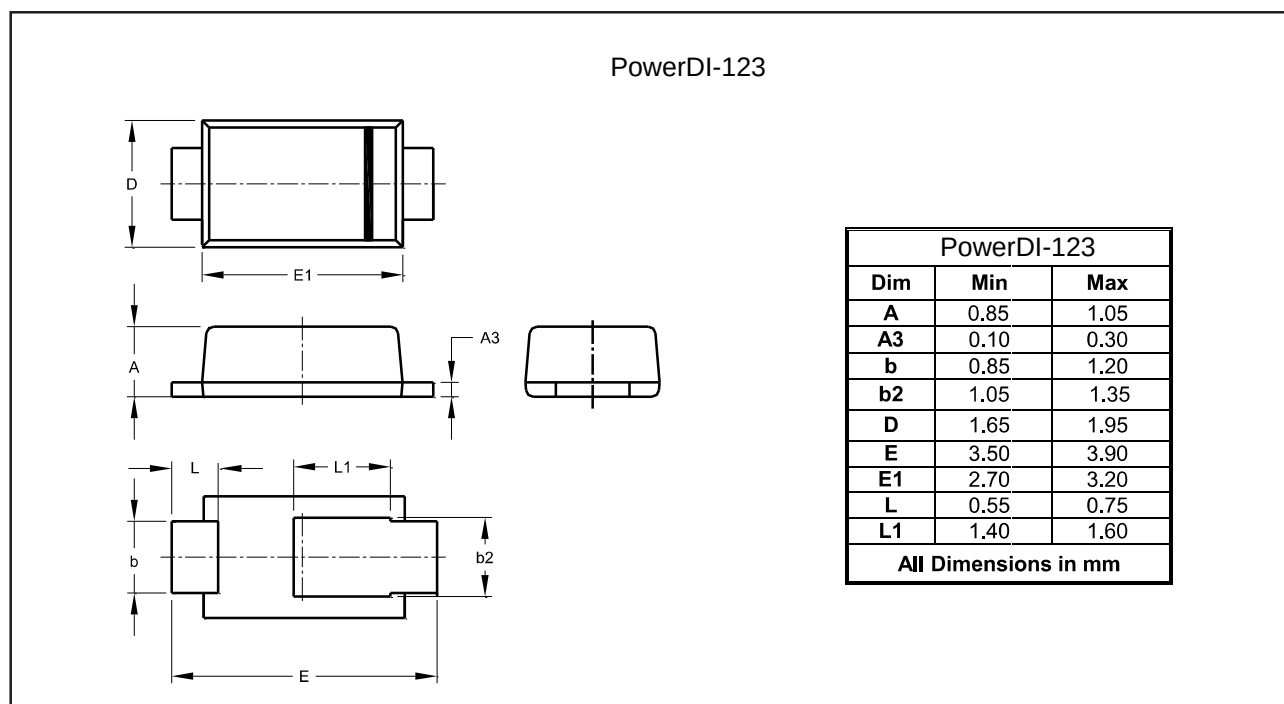
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

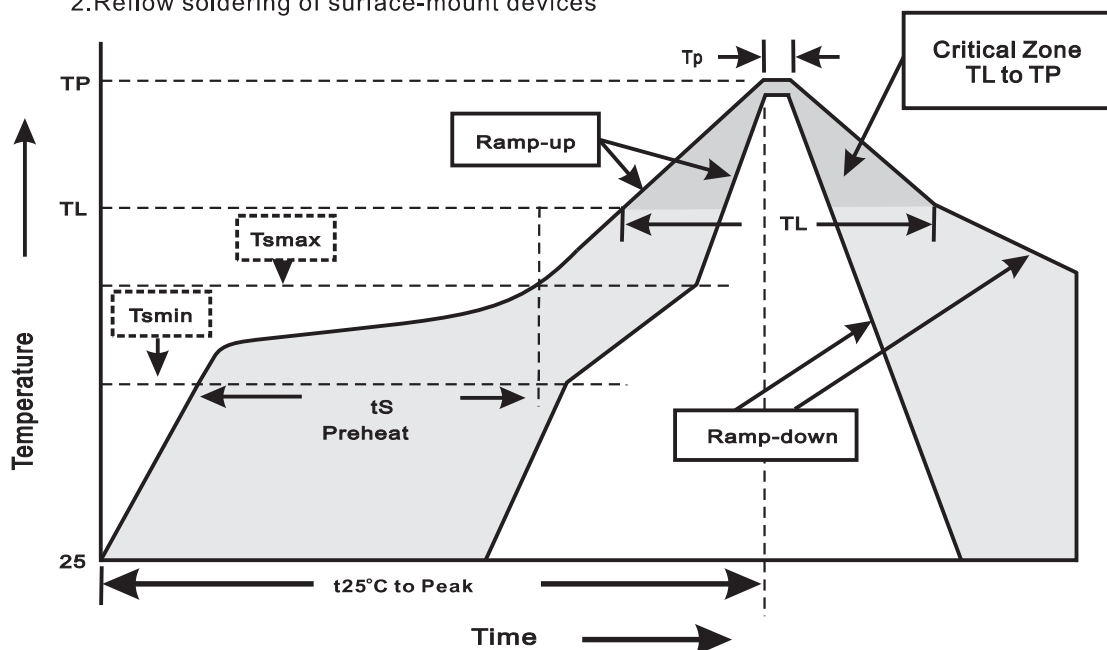
Type number	Marking code
DFLS1100	F09A

Package outline



Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{smin}) -Temperature Max(T _{smax}) -Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{smax} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes